SOLID STATE OPTRONICS

AD4C743

1 Form A / 1 Form B
60V / 1Ω
MOSFET Output Solid State Relay

Description

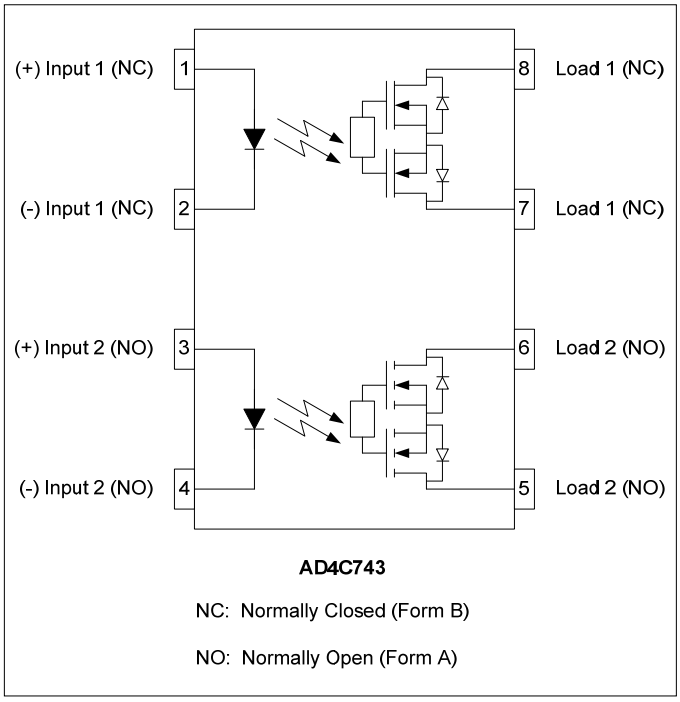
The AD4C743 is composed of two isolated relays; one normally open and one normally closed. Each relay has a bi-directional, single-pole, single-throw contact. Completely independent of its counterpart, each consists of an LED driver that activates an integrated circuit, which in turn drives a pair of DMOS transistors. The low on resistance (500mΩ TYP) and high load current rating (800mA) make this relay a unique and unparalleled product.

The AD4C743 comes standard in a compact 8 pin DIP package making it ideal for high-density board applications.

Applications

- Meter Reading Systems
- Multiplexers
- Data Acquisition
- Medical Equipment
- Battery Monitoring
- Home / Safety Security Systems

Schematic Diagram



AD4C743

NC: Normally Closed (Form B)

NO: Normally Open (Form A)

Features

- 1 Form A / 1 Form B Integrated in Single Package
- Low Input Control Current (2.5mA TYP)
- 800mA Maximum Continuous Load Current (per Channel)
- Low On Resistance (500mΩ TYP)
- High Isolation Voltage (up to 5kV$_{RMS}$)
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

Agency Approvals

UL/C-UL:	File # E201932
VDE:	File # 40035191 (EN 60747-5-2)

Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature .....-55 to +125°C
Operating Temperature .....-40 to +85°C
Continuous Input Current.....50mA
Transient Input Current.....500mA
Reverse Input Control Voltage 5V
Input Power Dissipation.....40mW
Output Power Dissipation 800mW
Solder Temperature – Wave (10sec).....260°C
Solder Temperature – IR Reflow (10sec).....260°C

Ordering Information

Part Number	Description
AD4C743	8 pin DIP, (50/Tube)
AD4C743-H	5kV$_{RMS}$ Viso, 8 pin DIP, (50/Tube)
AD4C743-S	8 pin SMD, (50/Tube)
AD4C743-HS	5kV$_{RMS}$, 8 pin SMD, (50/Tube)
AD4C743-STR	8 pin SMD, Tape and Reel (1000/Reel)
AD4C743-HSTR	5kV$_{RMS}$, 8 pin SMD, Tape and Reel (1000/Reel)

NOTE: Suffixes listed above are not included in marking on device for part number identification

Electrical Characteristics, T_A = 25°C (unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Specifications						
LED Forward Voltage	V_F	-	1.2	1.5	V	I_F = 10mA
LED Reverse Voltage	BV_R	5	-	-	V	I_R = 10µA
Turn-On Current (Form A – Normally Open)	$I_{F(NO)}$	-	2.5	5	mA	I_O = 800mA
Turn-On Current (Form B – Normally Closed)	$I_{F(NC)}$	-	0.5	-	mA	I_O = 800mA
Turn-Off Current (Form A – Normally Open)	$I_{FOFF(NO)}$	-	0.5	-	mA	I_O = 800mA
Turn-Off Current (Form B – Normally Open)	$I_{FOFF(NC)}$	-	2.5	5	mA	I_O = 800mA
Output Specifications – Form A (Normally Open)						
Blocking Voltage	V_B	60	-	-	V	I_O=1µA
Continuous Load Current	I_O	-	-	800	mA	I_F=5mA
On Resistance	R_{ON}	-	0.5	1	Ω	I_F=5mA, I_O=800mA
Leakage Current	I_{Oleak}	-	0.2	1	µA	I_F=0mA, V_O=60V
Output Capacitance	C_{OUT}	-	20	-	pF	V_O=25V, f=1.0MHz
Offset Voltage	V_{OFFSET}	-	-	0.2	mV	I_F=5mA
Turn-On Time	T_{ON}	-	3	5	mS	I_F=5mA, I_O=800mA
Turn-Off Time	T_{OFF}	-	0.05	5	mS	I_F=0mA, I_O=800mA
Output Specifications – Form B (Normally Closed)						
Blocking Voltage	V_B	60	-	-	V	I_F=5mA, I_O=1µA
Continuous Load Current	I_O	-	-	800	mA	I_F=0mA
On Resistance	R_{ON}	-	0.5	1	Ω	I_F=0mA, I_O=800mA
Leakage Current	I_{Oleak}	-	0.2	1	µA	I_F=5mA, V_O=60V
Output Capacitance	C_{OUT}	-	20	-	pF	I_F=5mA, f=1.0MHz
Offset Voltage	V_{OFFSET}	-	-	0.2	mV	I_F=0mA
Turn-On Time	T_{ON}	-	0.1	5	mS	I_F=0mA, I_O=800mA
Turn-Off Time	T_{OFF}	-	3	5	mS	I_F=5mA, I_O=800mA
Coupled Specifications						
Coupled Capacitance	$C_{COUPLED}$	-	3	-	pF	
Contact Transient Ratio	-	2,000	7,000	0	V/µS	dV = 50V
Isolation Specifications						
Isolation Voltage	V_{ISO}	3750	-	-	V_{RMS}	RH ≤ 50%, t=1min
(-H Option)		5000	-	-		
Input-Output Resistance	R_{I-O}	-	10^{12}	-	Ω	V_{I-O} = 500V_{DC}

AD4C743 Performance & Characteristics Plots, T_A = 25°C (unless otherwise specified)

Figure 1: *Normally Open*
Typical Turn-On Time Distribution
(N = 100, T_a = 25ºC)

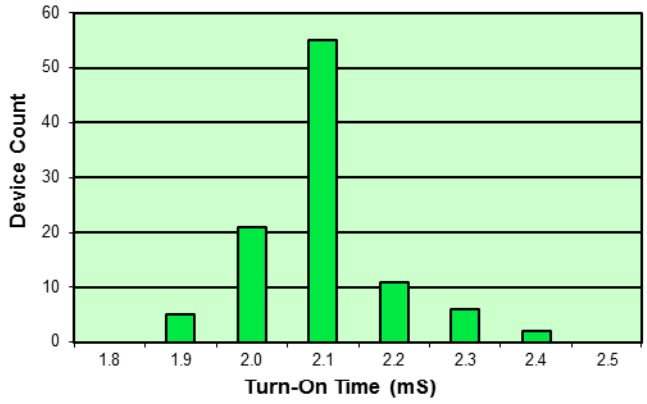


Figure 2: *Normally Open*
Typical Turn-Off Time Distribution
(N = 100, T_a = 25ºC)

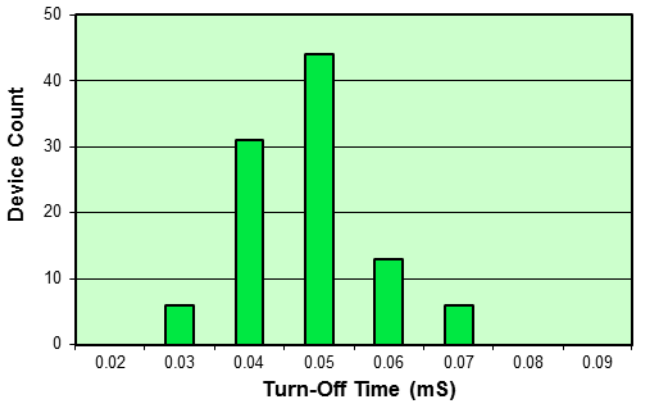


Figure 3: *Normally Open*
Typical On-Resistance Distribution
(N = 100, T_a = 25ºC)

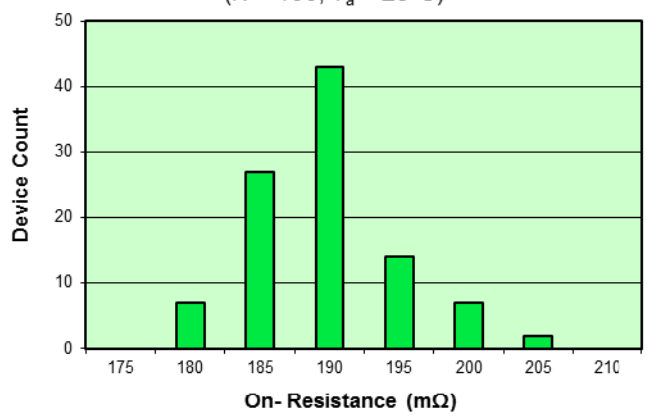


Figure 4: *Normally Open*
Typical Output Leakage Current Distribution
(N = 100, T_a = 25ºC)

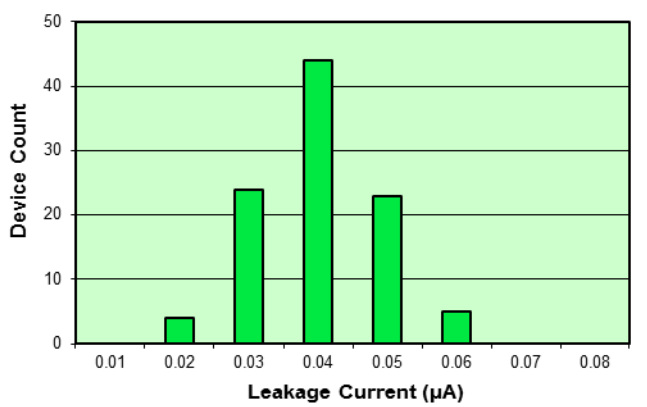


Figure 5: *Normally Open*
Typical Blocking Voltage Distribution
(N = 100, Ta = 25ºC)

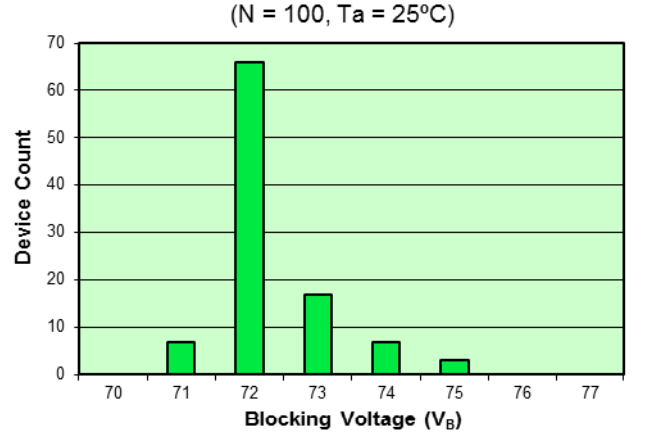
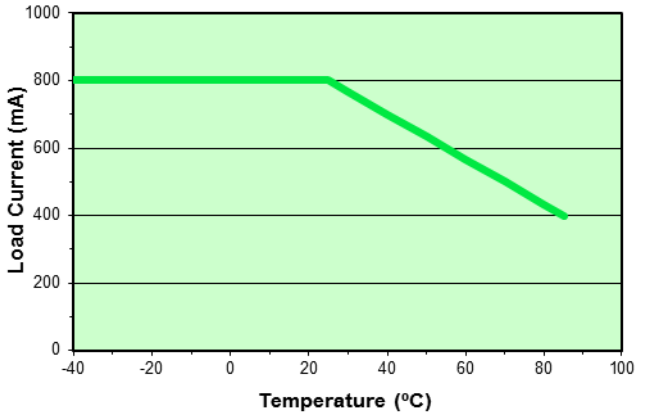


Figure 6: *Normally Open*
Maximum Load Current vs. Temperature



AD4C743 Performance & Characteristics Plots, Cont… T_A = 25°C (unless otherwise specified)

Figure 7: *Normally Closed*
Typical Turn-On Time Distribution
(N = 100, T_a = 25ºC)

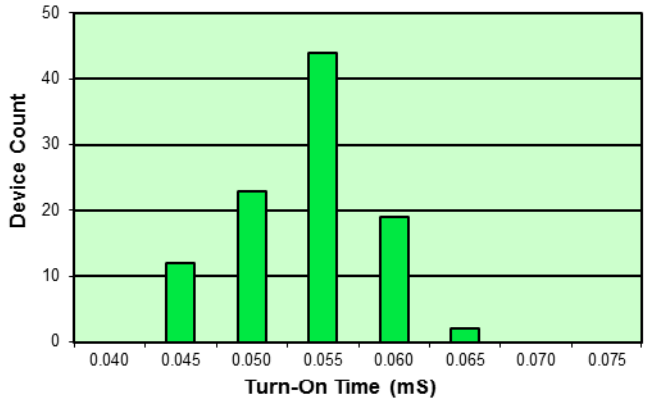


Figure 8: *Normally Closed*
Typical Turn-Off Time Distribution
(N = 100, T_a = 25ºC)

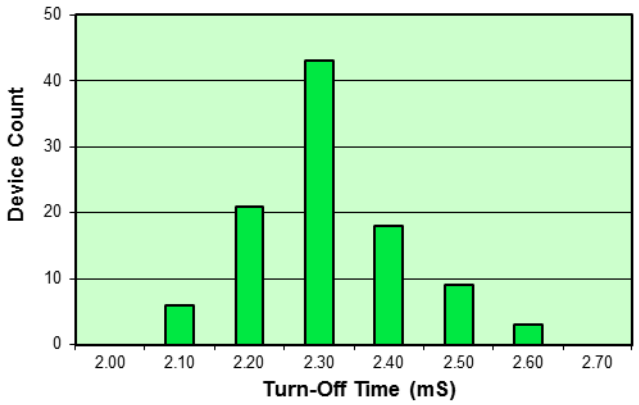


Figure 9: *Normally Closed*
Typical On-Resistance Distribution
(N = 100, T_a = 25ºC)

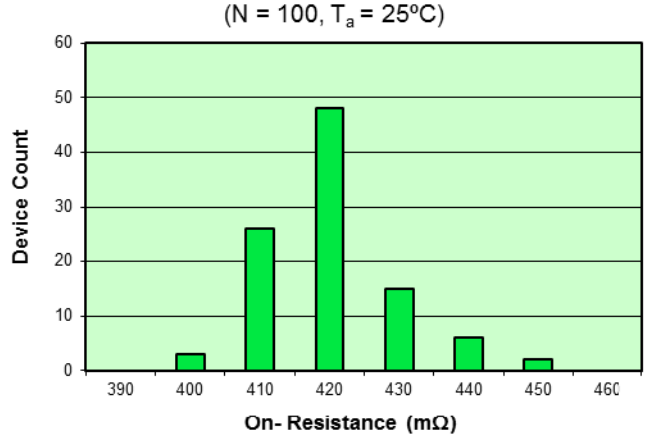


Figure 10: *Normally Closed*
Typical Output Leakage Current Distribution
(N = 100, T_a = 25ºC)

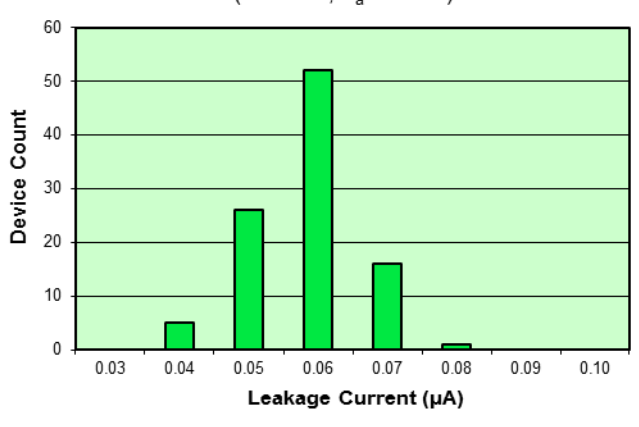


Figure 11: *Normally Closed*
Typical Blocking Voltage Distribution
(N = 100, Ta = 25ºC)

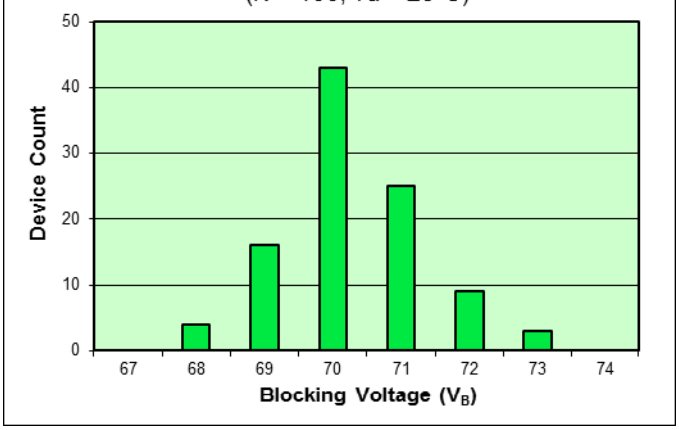
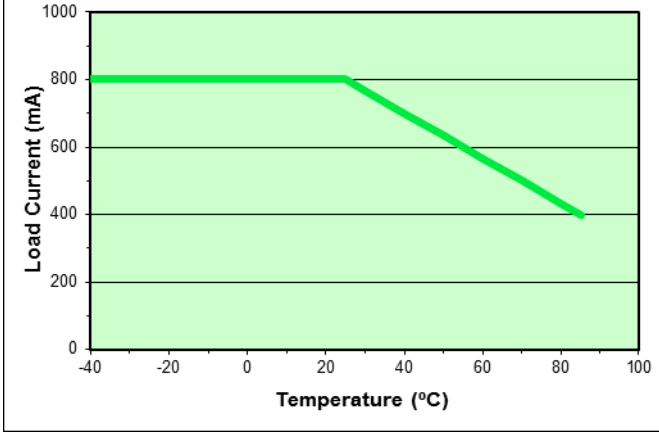


Figure 12: *Normally Closed*
Maximum Load Current vs. Temperature



AD4C743 Solder Temperature Profile Recommendations

(1) *Infrared Reflow:*

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250ºC:

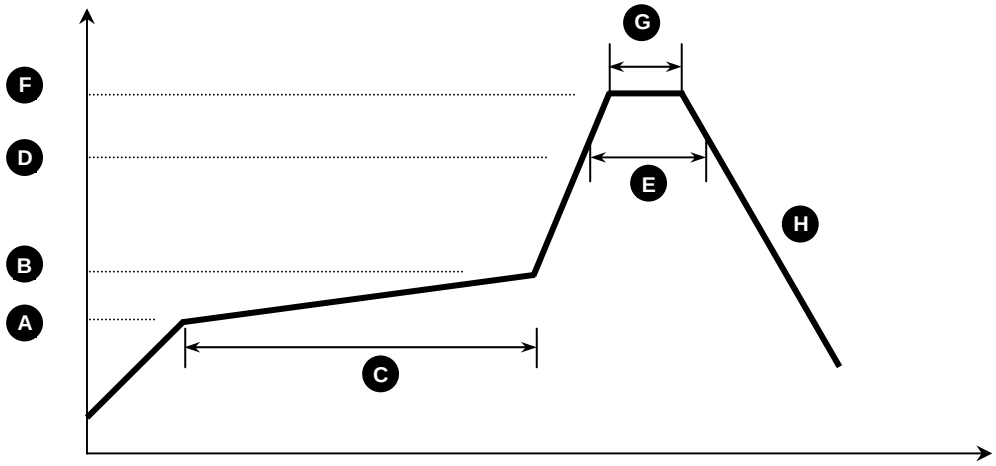


Figure 1

Process Step	Description	Parameter
A	Preheat Start Temperature (ºC)	150ºC
B	Preheat Finish Temperature (ºC)	180ºC
C	Preheat Time (s)	90 - 120s
D	Melting Temperature (ºC)	230ºC
E	Time above Melting Temperature (s)	30s
F	Peak Temperature, at Terminal (ºC)	260ºC
G	Dwell Time at Peak Temperature (s)	10s
H	Cool-down (ºC/s)	<6ºC/s

(2) *Wave Solder:*

Maximum Temperature:	260ºC (at terminal)
Maximum Time:	10s
Pre-heating:	100 - 150ºC (30 - 90s)
Single Occurrence	

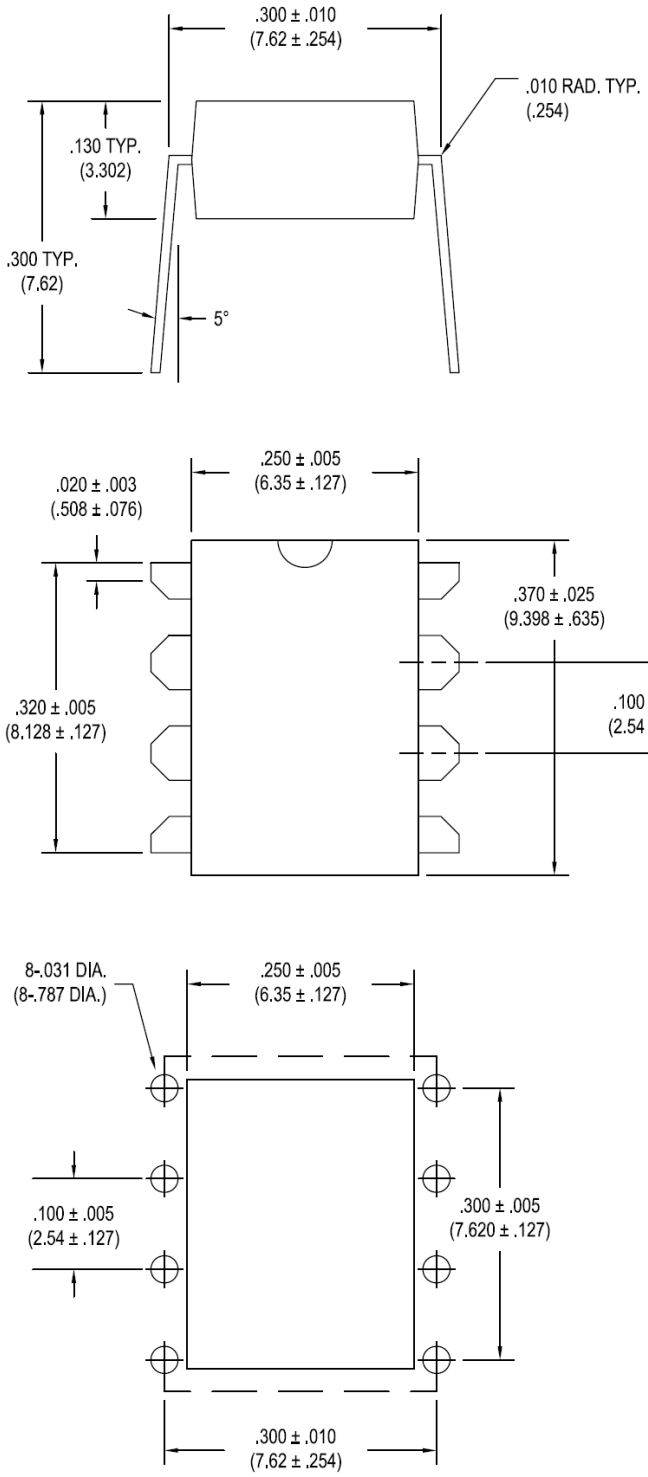
(3) *Hand Solder:*

Maximum Temperature:	350ºC (at tip of soldering iron)
Maximum Time:	3s
Single Occurrence	

AD4C743 Package Dimensions

8 PIN DIP Package

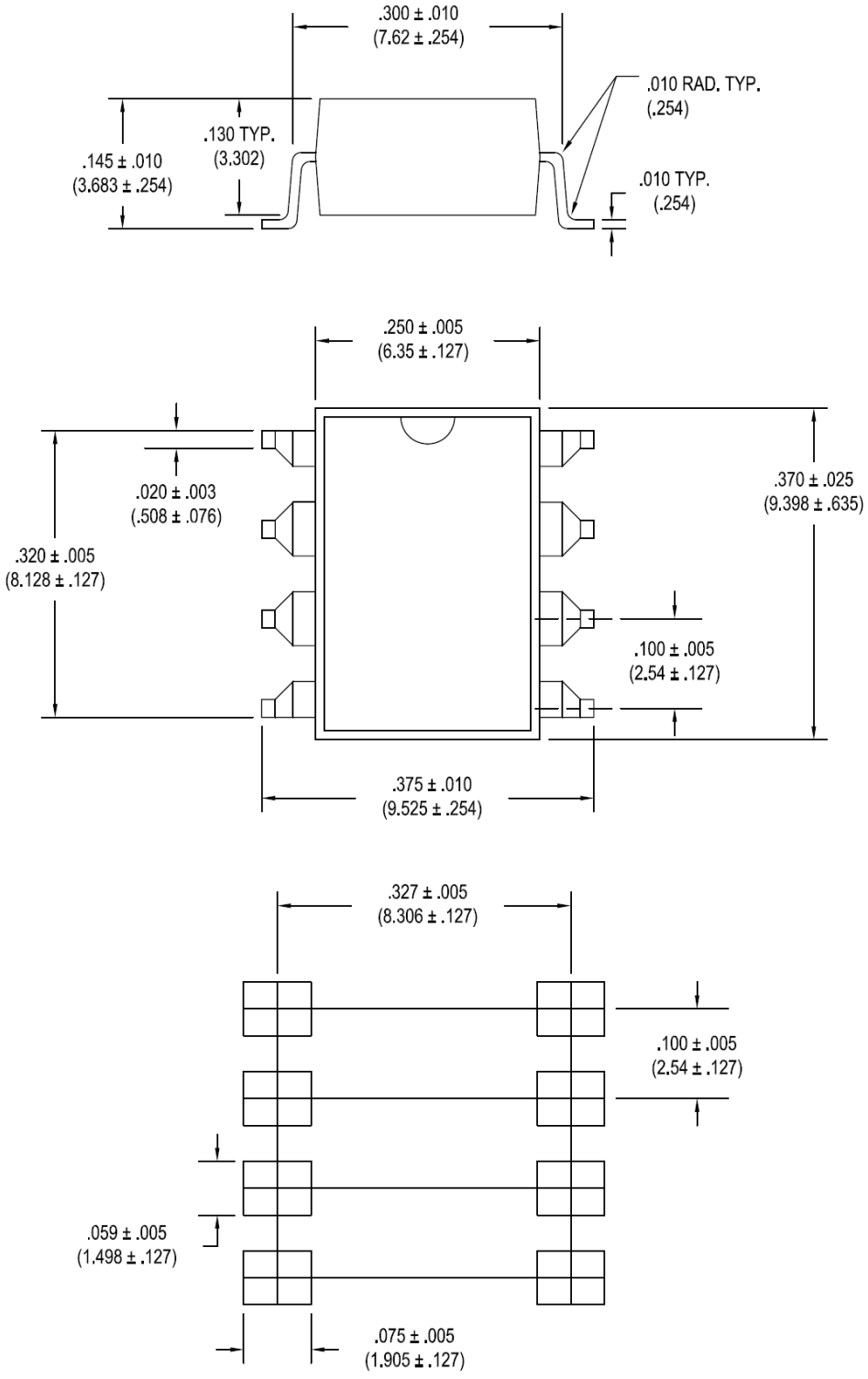
Note: *All dimensions in inches ["] with millimeters in parenthesis ()*



AD4C743 Package Dimensions

8 PIN SMD Surface Mount Package (-S)

Note: *All dimensions in inches ["] with millimeters in parenthesis ()*

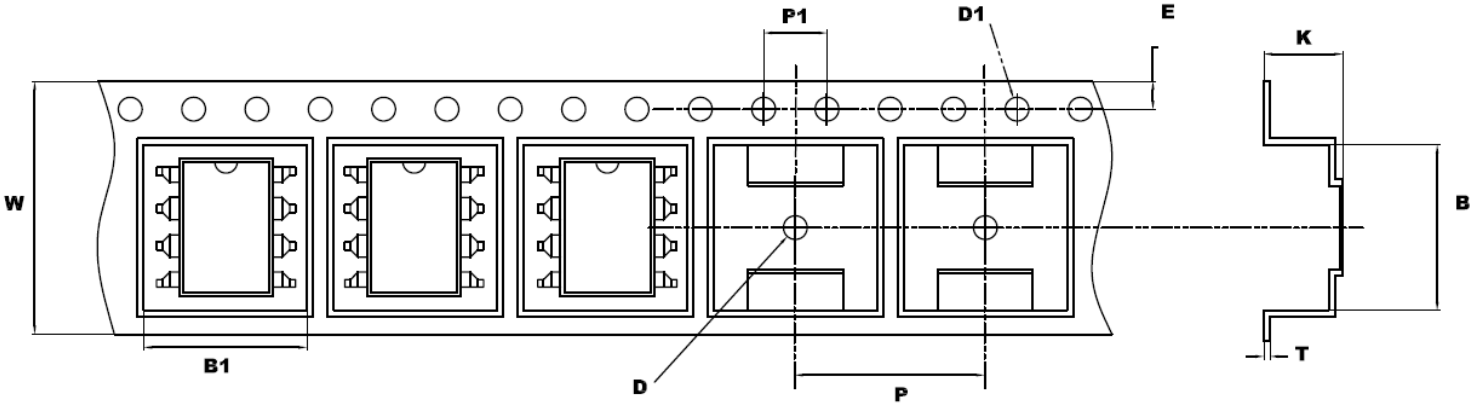


AD4C743 Package Dimensions

8 PIN SMD Tape & Reel (-STR)

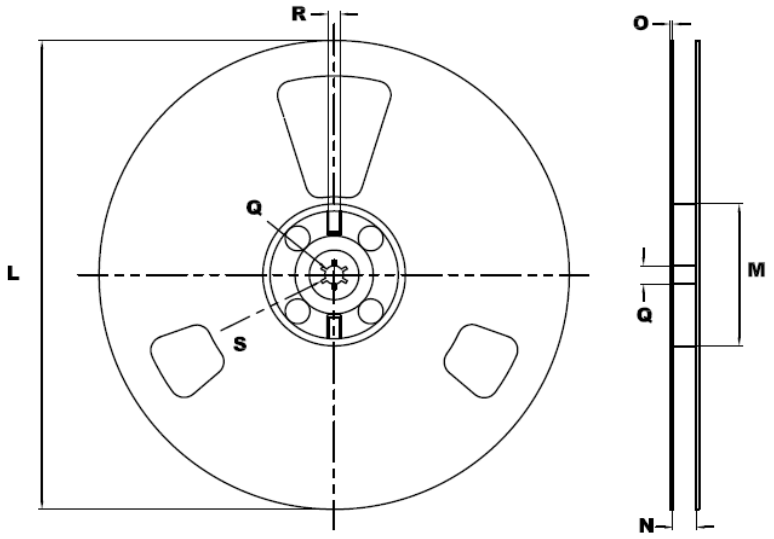
Note: *All dimensions in millimeters*

Outline and Dimension (Tape)



W	B	B1	P	P1	K	E	T	D	D1
16.00 ±0.1	10.50 ±0.1	10.30 ±0.1	12.00 ±0.1	4.00 ±0.1	5.00 ±0.1	1.75 ±0.1	0.40 ±0.1	1.50 ±0.1	1.50 ±0.1

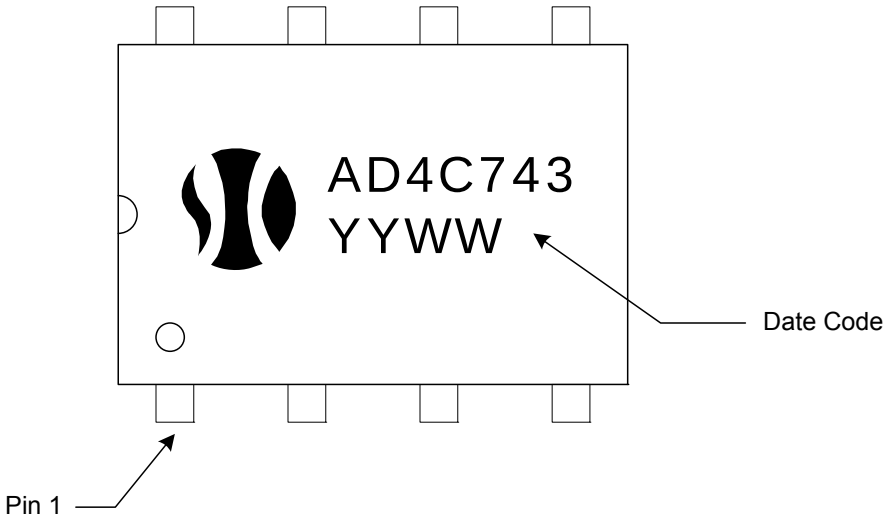
Outline and Dimensions (Reel)



Packaging: 1,000 pcs / reel

L	M	N	O	Q	R	S
330.00	100.00	16.40 +0.2	2.00 ±0.1	13.00 ±0.2	2.00	10.00

AD4C743 Package Marking



AD4C743 Package Weights

Device	Single Unit	Full Tube (50pcs)	Full Pouch (10 tubes)	Full Reel (1000pcs)
AD4C743-(H)	0.54	42	420	-
AD4C743-(H)S	0.53	44	440	-
AD4C743-(H)STR	0.53	-	-	950

Note: *All weights above are in GRAMS, and include packaging materials where applicable*

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